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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I ² C, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	30-LSSOP (0.240", 6.10mm Width)
Supplier Device Package	30-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f102a8dsp-x0

○ ROM, RAM capacities

Code flash	Data flash	RAM	20 pins	24 pins	30 pins
16 KB	2 KB	2 KB	—	—	R5F102AA
	—		—	—	R5F103AA
	2 KB	1.5 KB	R5F1026A ^{Note 1}	R5F1027A ^{Note 1}	—
	—		R5F1036A ^{Note 1}	R5F1037A ^{Note 1}	—
12 KB	2KB	1 KB	R5F10269 ^{Note 1}	R5F10279 ^{Note 1}	R5F102A9
	—		R5F10369 ^{Note 1}	R5F10379 ^{Note 1}	R5F103A9
8 KB	2 KB	768 B	R5F10268 ^{Note 1}	R5F10278 ^{Note 1}	R5F102A8
	—		R5F10368 ^{Note 1}	R5F10378 ^{Note 1}	R5F103A8
4 KB	2KB	512 B	R5F10267	R5F10277	R5F102A7
	—		R5F10367	R5F10377	R5F103A7
2 KB	2 KB	256 B	R5F10266 ^{Note 2}	—	—
	—		R5F10366 ^{Note 2}	—	—

Notes 1. This is 640 bytes when the self-programming function or data flash function is used. (For details, see **CHAPTER 3 CPU ARCHITECTURE**.)

2. The self-programming function cannot be used for R5F10266 and R5F10366.

Caution When the flash memory is rewritten via a user program, the code flash area and RAM area are used because each library is used. When using the library, refer to RL78 Family Flash Self Programming Library Type01 User's Manual and RL78 Family Data Flash Library Type04 User's Manual.

<R> 2. ELECTRICAL SPECIFICATIONS ($T_A = -40$ to $+85^\circ\text{C}$)

<R> This chapter describes the following electrical specifications.

Target products A: Consumer applications $T_A = -40$ to $+85^\circ\text{C}$

<R> R5F102xxAxx, R5F103xxAxx

D: Industrial applications $T_A = -40$ to $+85^\circ\text{C}$

<R> R5F102xxDxx, R5F103xxDxx

G: Industrial applications when $T_A = -40$ to $+105^\circ\text{C}$ products is used in the range of $T_A = -40$ to $+85^\circ\text{C}$

<R> R5F102xxGxx

Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.

2. The pins mounted depend on the product. Refer to 2.1 Port Functions to 2.2.1 Functions for each product.

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)**(2/4)**

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current, low ^{Note 1}	I _{OL1}	20-, 24-pin products: Per pin for P00 to P03 ^{Note 4} , P10 to P14, P40 to P42			20.0 ^{Note 2}	mA
		30-pin products: Per pin for P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147				
		Per pin for P60, P61			15.0 ^{Note 2}	mA
		20-, 24-pin products: Total of P40 to P42	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$		60.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$		9.0	mA
		30-pin products: Total of P00, P01, P40, P120 (When duty $\leq 70\%$ ^{Note 3})	$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$		1.8	mA
		20-, 24-pin products: Total of P00 to P03 ^{Note 4} , P10 to P14, P60, P61	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$		80.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$		27.0	mA
		30-pin products: Total of P10 to P17, P30, P31, P50, P51, P60, P61, P147 (When duty $\leq 70\%$ ^{Note 3})	$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$		5.4	mA
		Total of all pins (When duty $\leq 70\%$ ^{Note 3})			140	mA
	I _{OL2}	Per pin for P20 to P23			0.4	mA
		Total of all pins			1.6	mA

Notes 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin.

2. However, do not exceed the total current value.

3. The output current value under conditions where the duty factor $\leq 70\%$.

If duty factor $> 70\%$: The output current value can be calculated with the following expression (where n represents the duty factor as a percentage).

- Total output current of pins = $(I_{OL} \times 0.7)/(n \times 0.01)$

<Example> Where $n = 80\%$ and $I_{OL} = 10.0\text{ mA}$

$$\text{Total output current of pins} = (10.0 \times 0.7)/(80 \times 0.01) \cong 8.7\text{ mA}$$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. 24-pin products only.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(2) 30-pin products

 $(T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)

(2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit	
Supply current ^{Note 1}	I _{DD2} ^{Note 2}	HALT mode	HS (High-speed main) mode ^{Note 6}	f _{IH} = 24 MHz ^{Note 4}	V _{DD} = 5.0 V		440	1280	μA	
					V _{DD} = 3.0 V		440	1280		
				f _{IH} = 16 MHz ^{Note 4}	V _{DD} = 5.0 V		400	1000	μA	
					V _{DD} = 3.0 V		400	1000		
				LS (Low-speed main) mode ^{Note 6}	f _{IH} = 8 MHz ^{Note 4}	V _{DD} = 3.0 V		260	530	μA
						V _{DD} = 2.0 V		260	530	
			HS (High-speed main) mode ^{Note 6}	f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input		280	1000	μA	
					Resonator connection		450	1170		
				f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		280	1000	μA	
					Resonator connection		450	1170		
				f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input		190	600	μA	
					Resonator connection		260	670		
				f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		190	600	μA	
					Resonator connection		260	670		
			LS (Low-speed main) mode ^{Note 6}	f _{MX} = 8 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		95	330	μA	
					Resonator connection		145	380		
				f _{MX} = 8 MHz ^{Note 3} , V _{DD} = 2.0 V	Square wave input		95	330	μA	
					Resonator connection		145	380		
	I _{DD3} ^{Note 5}	STOP mode	T _A = −40°C					0.18	0.50	μA
			T _A = +25°C					0.23	0.50	
			T _A = +50°C					0.30	1.10	
			T _A = +70°C					0.46	1.90	
			T _A = +85°C					0.75	3.30	

Notes 1. Total current flowing into V_{DD} , including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS} . The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator clock is stopped.

4. When high-speed system clock is stopped.

5. Not including the current flowing into the 12-bit interval timer and watchdog timer.

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as follows.

HS (High speed main) mode: $V_{DD} = 2.7\text{ V}$ to 5.5 V @ 1 MHz to 24 MHz

$V_{DD} = 2.4\text{ V}$ to 5.5 V @ 1 MHz to 16 MHz

LS (Low speed main) mode: $V_{DD} = 1.8\text{ V}$ to 5.5 V @ 1 MHz to 8 MHz

Remarks 1. f_{MX} : High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH} : high-speed on-chip oscillator clock frequency

3. Except STOP mode, temperature condition of the TYP. value is $T_A = 25^\circ\text{C}$.

(2) During communication at same potential (CSI mode) (master mode, SCK00... internal clock output, corresponding CSI00 only)

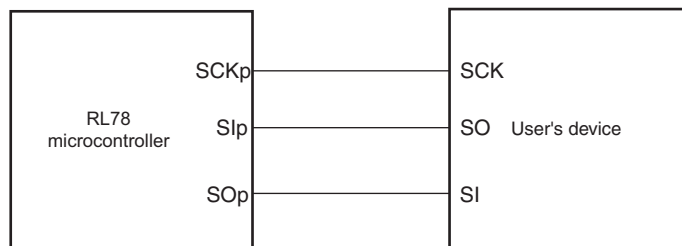
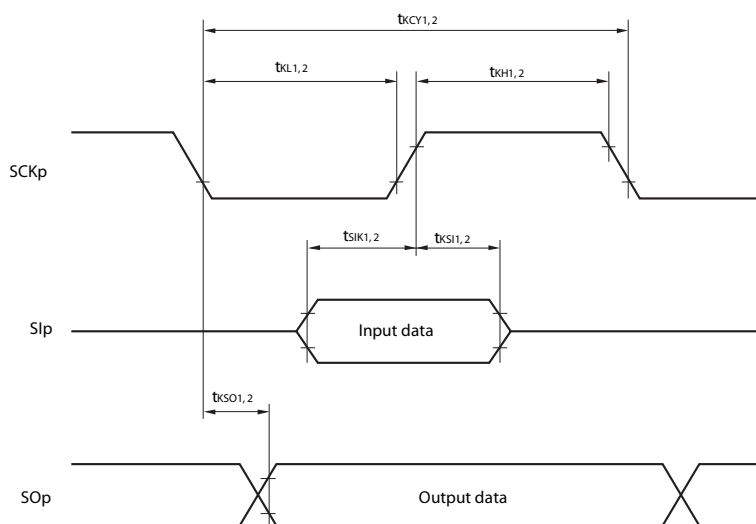
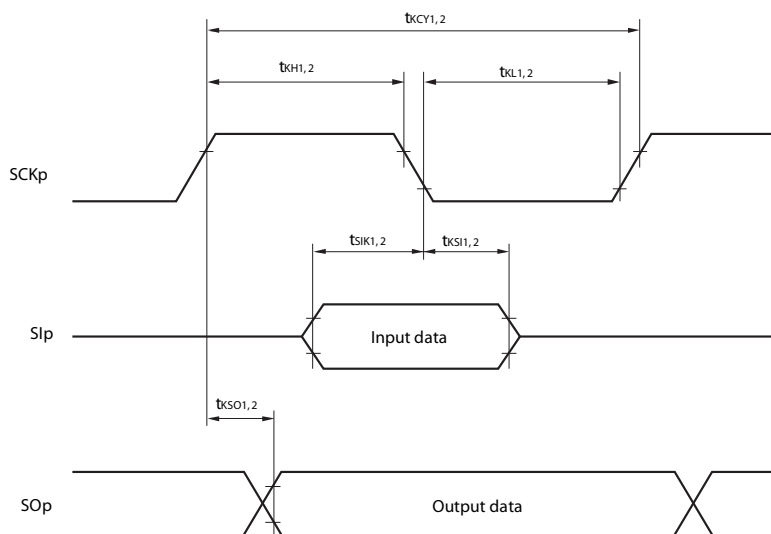
(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
SCK00 cycle time	t _{KCY1}	t _{KCY1} ≥ 2/f _{CLK}	83.3		250		ns
SCK00 high-/low-level width	t _{KH1} , t _{KL1}	4.0 V ≤ V _{DD} ≤ 5.5 V	t _{KCY1} /2-7		t _{KCY1} /2-50		ns
		2.7 V ≤ V _{DD} ≤ 5.5 V	t _{KCY1} /2-10		t _{KCY1} /2-50		ns
SI00 setup time (to SCK00↑) ^{Note 1}	t _{SIK1}	4.0 V ≤ V _{DD} ≤ 5.5 V	23		110		ns
		2.7 V ≤ V _{DD} ≤ 5.5 V	33		110		ns
SI00 hold time (from SCK00↑) ^{Note 2}	t _{KSI1}		10		10		ns
Delay time from SCK00↓ to SO00 output ^{Note 3}	t _{KSO1}	C = 20 pF ^{Note 4}		10		10	ns

- Notes**
1. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The SI00 setup time becomes “to SCK00↓” when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.
 2. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The SI00 hold time becomes “from SCK00↓” when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.
 3. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The delay time to SO00 output becomes “from SCK00↑” when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.
 4. C is the load capacitance of the SCK00 and SO00 output lines.

Caution Select the normal input buffer for the SI00 pin and the normal output mode for the SO00 and SCK00 pins by using port input mode register 1 (PIM1) and port output mode register 1 (POM1).

- Remarks**
1. This specification is valid only when CSI00's peripheral I/O redirect function is not used.
 2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the serial clock select register 0 (SPS0) and the CKS00 bit of serial mode register 00 (SMR00).)

CSI mode connection diagram (during communication at same potential)
CSI mode serial transfer timing (during communication at same potential)
 (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

CSI mode serial transfer timing (during communication at same potential)
 (When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)


(Remarks are listed on the next page.)

5. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 4** above to calculate the maximum transfer rate under conditions of the customer.

6. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.7 V ≤ V_{DD} < 4.0 V and 2.3 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \quad [\text{bps}]$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

7. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 6** above to calculate the maximum transfer rate under conditions of the customer.

8. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\} \times 3} \quad [\text{bps}]$$

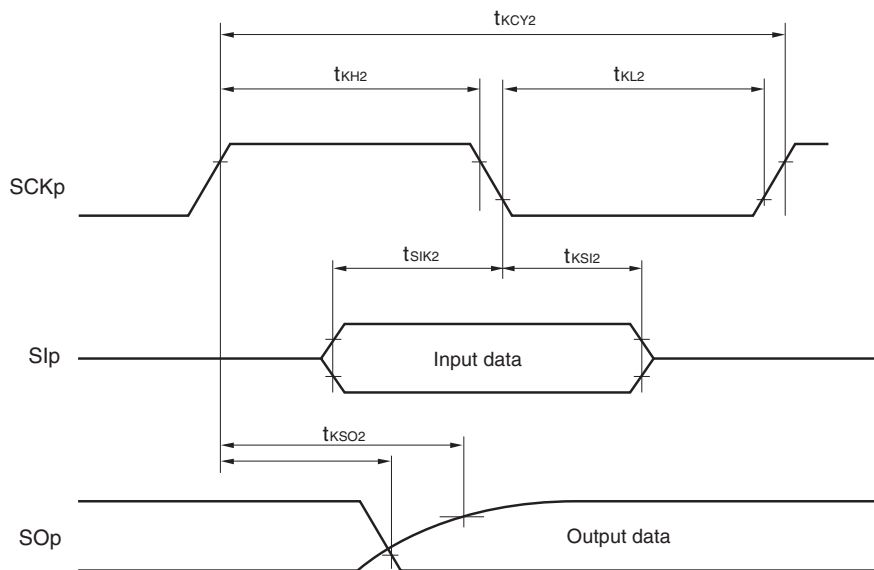
$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

9. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 8** above to calculate the maximum transfer rate under conditions of the customer.

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

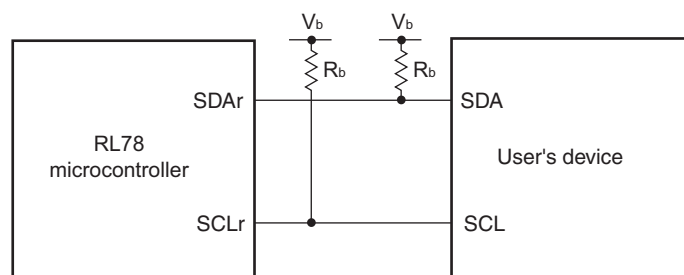
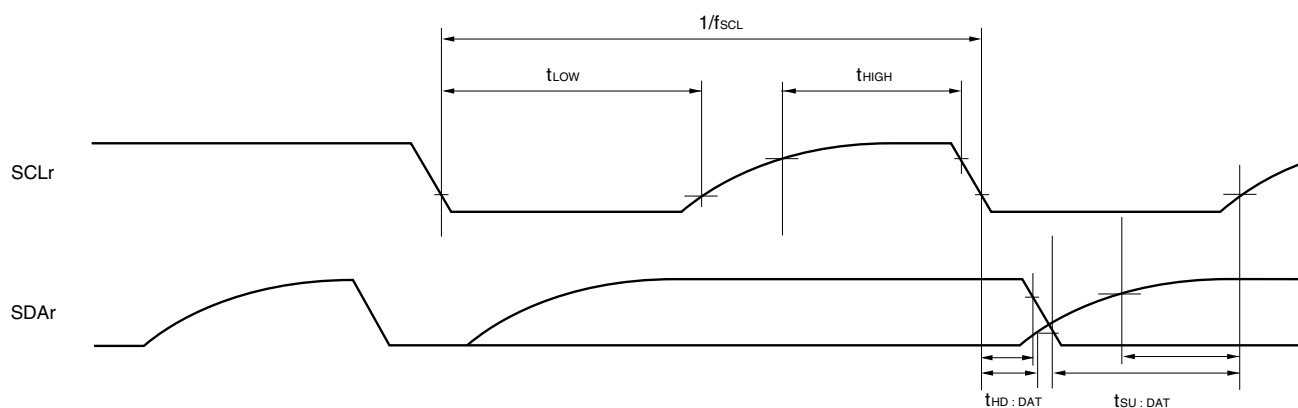
(10) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified I²C mode)**($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
SCLr clock frequency	f_{SCL}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.7\text{ V} \leq V_b \leq 4.0\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.8\text{ k}\Omega$		400 ^{Note1}		300 ^{Note1}	kHz
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$, $2.3\text{ V} \leq V_b \leq 2.7\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.7\text{ k}\Omega$		400 ^{Note1}		300 ^{Note1}	kHz
		$1.8\text{ V} \leq V_{DD} < 3.3\text{ V}$, $1.6\text{ V} \leq V_b \leq 2.0\text{ V}$, ^{Note2} $C_b = 100\text{ pF}$, $R_b = 5.5\text{ k}\Omega$		300 ^{Note1}		300 ^{Note1}	kHz
Hold time when SCLr = "L"	t_{LOW}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.7\text{ V} \leq V_b \leq 4.0\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.8\text{ k}\Omega$	1150		1550		ns
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$, $2.3\text{ V} \leq V_b \leq 2.7\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.7\text{ k}\Omega$	1150		1550		ns
		$1.8\text{ V} \leq V_{DD} < 3.3\text{ V}$, $1.6\text{ V} \leq V_b \leq 2.0\text{ V}$, ^{Note2} $C_b = 100\text{ pF}$, $R_b = 5.5\text{ k}\Omega$	1550		1550		ns
Hold time when SCLr = "H"	t_{HIGH}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.7\text{ V} \leq V_b \leq 4.0\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.8\text{ k}\Omega$	675		610		ns
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$, $2.3\text{ V} \leq V_b \leq 2.7\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.7\text{ k}\Omega$	600		610		ns
		$1.8\text{ V} \leq V_{DD} < 3.3\text{ V}$, $1.6\text{ V} \leq V_b \leq 2.0\text{ V}$, ^{Note2} $C_b = 100\text{ pF}$, $R_b = 5.5\text{ k}\Omega$	610		610		ns
Data setup time (reception)	$t_{SU:DAT}$	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.7\text{ V} \leq V_b \leq 4.0\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.8\text{ k}\Omega$	$1/f_{MCK}$ + 190 ^{Note3}		$1/f_{MCK}$ + 190 ^{Note3}		ns
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$, $2.3\text{ V} \leq V_b \leq 2.7\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.7\text{ k}\Omega$	$1/f_{MCK}$ + 190 ^{Note3}		$1/f_{MCK}$ + 190 ^{Note3}		ns
		$1.8\text{ V} \leq V_{DD} < 3.3\text{ V}$, $1.6\text{ V} \leq V_b \leq 2.0\text{ V}$, ^{Note2} $C_b = 100\text{ pF}$, $R_b = 5.5\text{ k}\Omega$	$1/f_{MCK}$ + 190 ^{Note3}		$1/f_{MCK}$ + 190 ^{Note3}		ns
Data hold time (transmission)	$t_{HD:DAT}$	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $2.7\text{ V} \leq V_b \leq 4.0\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.8\text{ k}\Omega$	0	355	0	355	ns
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$, $2.3\text{ V} \leq V_b \leq 2.7\text{ V}$, $C_b = 100\text{ pF}$, $R_b = 2.7\text{ k}\Omega$	0	355	0	355	ns
		$1.8\text{ V} \leq V_{DD} < 3.3\text{ V}$, $1.6\text{ V} \leq V_b \leq 2.0\text{ V}$, ^{Note2} $C_b = 100\text{ pF}$, $R_b = 5.5\text{ k}\Omega$	0	405	0	405	ns

Notes 1. The value must also be equal to or less than $f_{MCK}/4$.2. Use it with $V_{DD} \geq V_b$.3. Set $t_{SU:DAT}$ so that it will not exceed the hold time when SCLr = "L" or SCLr = "H".**Cautions** 1. Select the TTL input buffer and the N-ch open drain output (V_{DD} tolerance) mode for the SDAr pin and the N-ch open drain output (V_{DD} tolerance) mode for the SCLr pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL} , see the DC characteristics with TTL input buffer selected.

2. IIC01 and IIC11 cannot communicate at different potential.

(Remarks are listed on the next page.)

Simplified I²C mode connection diagram (during communication at different potential)**Simplified I²C mode serial transfer timing (during communication at different potential)**

- Remarks**
1. R_b [Ω]: Communication line (SDAr, SCLr) pull-up resistance, C_b [F]: Communication line (SDAr, SCLr) load capacitance, V_b [V]: Communication line voltage
 2. r : IIC Number ($r = 00, 20$)
 3. f_{MCK} : Serial array unit operation clock frequency
(Operation clock to be set by the serial clock select register m (SPS m) and the CKS m n bit of serial mode register m n (SMR m n).
 m : Unit number ($m = 0, 1$), n : Channel number ($n = 0$))
 4. Simplified I²C mode is supported only by the R5F102 products.

<R> 3. ELECTRICAL SPECIFICATIONS (G: INDUSTRIAL APPLICATIONS $T_A = -40$ to $+105^\circ\text{C}$)

<R> This chapter describes the following electrical specifications.

Target products G: Industrial applications $T_A = -40$ to $+105^\circ\text{C}$

<R> R5F102xxGxx

- Cautions**
1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
 2. The pins mounted depend on the product. Refer to 2.1 Port Functions to 2.2.1 Functions for each product.
 3. Please contact Renesas Electronics sales office for derating of operation under $T_A = +85^\circ\text{C}$ to $+105^\circ\text{C}$. Derating is the systematic reduction of load for the sake of improved reliability.

Remark When the RL78 microcontroller is used in the range of $T_A = -40$ to $+85^\circ\text{C}$, see CHAPTER 28
ELECTRICAL SPECIFICATIONS (A: $T_A = -40$ to $+85^\circ\text{C}$).

<R>

There are following differences between the products "G: Industrial applications ($T_A = -40$ to $+105^\circ\text{C}$)" and the products "A: Consumer applications, and D: Industrial applications".

Parameter	Application	
	A: Consumer applications, D: Industrial applications	G: Industrial applications
Operating ambient temperature	$T_A = -40$ to $+85^\circ\text{C}$	$T_A = -40$ to $+105^\circ\text{C}$
Operating mode Operating voltage range	HS (high-speed main) mode: $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ @ 1 MHz to 24 MHz $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ @ 1 MHz to 16 MHz LS (low-speed main) mode: $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ @ 1 MHz to 8 MHz	HS (high-speed main) mode only: $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ @ 1 MHz to 24 MHz $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ @ 1 MHz to 16 MHz
High-speed on-chip oscillator clock accuracy	R5F102 products, $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$: $\pm 1.0\%$ @ $T_A = -20$ to $+85^\circ\text{C}$ $\pm 1.5\%$ @ $T_A = -40$ to -20°C R5F103 products, $1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$: $\pm 5.0\%$ @ $T_A = -40$ to $+85^\circ\text{C}$	R5F102 products, $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$: $\pm 2.0\%$ @ $T_A = +85$ to $+105^\circ\text{C}$ $\pm 1.0\%$ @ $T_A = -20$ to $+85^\circ\text{C}$ $\pm 1.5\%$ @ $T_A = -40$ to -20°C
Serial array unit	UART CSI: $f_{CLK}/2$ (supporting 12 Mbps), $f_{CLK}/4$ Simplified I ² C communication	UART CSI: $f_{CLK}/4$ Simplified I ² C communication
Voltage detector	Rise detection voltage: 1.88 V to 4.06 V (12 levels) Fall detection voltage: 1.84 V to 3.98 V (12 levels)	Rise detection voltage: 2.61 V to 4.06 V (8 levels) Fall detection voltage: 2.55 V to 3.98 V (8 levels)

Remark The electrical characteristics of the products G: Industrial applications ($T_A = -40$ to $+105^\circ\text{C}$) are different from those of the products "A: Consumer applications, and D: Industrial applications". For details, refer to 29.1 to 29.10.

3.3 DC Characteristics

3.3.1 Pin characteristics

(T_A = -40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

(1/4)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current, high ^{Note 1}	I _{OH1}	20-, 24-pin products: Per pin for P00 to P03 ^{Note 4} , P10 to P14, P40 to P42 30-pin products: Per pin for P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147			-3.0 ^{Note 2}	mA
		20-, 24-pin products: Total of P40 to P42	4.0 V ≤ V _{DD} ≤ 5.5 V		-9.0	mA
		30-pin products: Total of P00, P01, P40, P120 (When duty ≤ 70% ^{Note 3})	2.7 V ≤ V _{DD} < 4.0 V		-6.0	mA
			2.4 V ≤ V _{DD} < 2.7 V		-4.5	mA
		20-, 24-pin products: Total of P00 to P03 ^{Note 4} , P10 to P14	4.0 V ≤ V _{DD} ≤ 5.5 V		-27.0	mA
			2.7 V ≤ V _{DD} < 4.0 V		-18.0	mA
		30-pin products: Total of P10 to P17, P30, P31, P50, P51, P147 (When duty ≤ 70% ^{Note 3})	2.4 V ≤ V _{DD} < 2.7 V		-10.0	mA
		Total of all pins (When duty ≤ 70% ^{Note 3})			-36.0	mA
	I _{OH2}	Per pin for P20 to P23			-0.1	mA
		Total of all pins			-0.4	mA

Notes 1. value of current at which the device operation is guaranteed even if the current flows from the V_{DD} pin to an output pin.

2. However, do not exceed the total current value.

3. The output current value under conditions where the duty factor ≤ 70%.

If duty factor > 70%: The output current value can be calculated with the following expression (where n represents the duty factor as a percentage).

- Total output current of pins = (I_{OH} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OH} = -10.0 mA

$$\text{Total output current of pins} = (-10.0 \times 0.7)/(80 \times 0.01) \cong -8.7 \text{ mA}$$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. 24-pin products only.

Caution P10 to P12 and P41 for 20-pin products, P01, P10 to P12, and P41 for 24-pin products, and P00, P10 to P15, P17, and P50 for 30-pin products do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

($T_A = -40$ to $+105^\circ\text{C}$, $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)**(4/4)**

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output voltage, low	V _{OL1}	20-, 24-pin products: P00 to P03 ^{Note} , P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	4.0 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 8.5 mA			0.7	V
			2.7 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 3.0 mA			0.6	V
			2.7 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 1.5 mA			0.4	V
			2.4 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 0.6 mA			0.4	V
	V _{OL2}	P20 to P23	I _{OL2} = 400 μA			0.4	V
	V _{OL3}	P60, P61	4.0 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 15.0 mA			2.0	V
			4.0 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 5.0 mA			0.4	V
			2.7 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 3.0 mA			0.4	V
			2.4 V $\leq V_{DD} \leq 5.5\text{ V}$, I _{OL1} = 2.0 mA			0.4	V
Input leakage current, high	I _{LIH1}	Other than P121, P122	V _I = V _{DD}			1	μA
	I _{LIH2}	P121, P122 (X1, X2/EXCLK)	V _I = V _{DD} Input port or external clock input			1	μA
			When resonator connected			10	μA
Input leakage current, low	I _{LIL1}	Other than P121, P122	V _I = V _{SS}			-1	μA
	I _{LIL2}	P121, P122 (X1, X2/EXCLK)	V _I = V _{SS} Input port or external clock input			-1	μA
			When resonator connected			-10	μA
On-chip pull-up resistance	R _U	20-, 24-pin products: P00 to P03 ^{Note} , P10 to P14, P40 to P42, P125, RESET 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	V _I = V _{SS} , input port	10	20	100	k Ω

Note 24-pin products only.**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(1) 20-, 24-pin products

(T_A = -40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

(2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current ^{Note 1}	I _{DD2} ^{Note 2}	HALT mode	HS (High-speed main) mode ^{Note 6}	f _{IH} = 24 MHz ^{Note 4}	V _{DD} = 5.0 V		440	2230	μA
					V _{DD} = 3.0 V		440	2230	
				f _{IH} = 16 MHz ^{Note 4}	V _{DD} = 5.0 V		400	1650	μA
					V _{DD} = 3.0 V		400	1650	
				f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input		280	1900	μA
					Resonator connection		450	2000	
				f _{MX} = 20 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		280	1900	μA
					Resonator connection		450	2000	
				f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 5.0 V	Square wave input		190	1010	μA
					Resonator connection		260	1090	
				f _{MX} = 10 MHz ^{Note 3} , V _{DD} = 3.0 V	Square wave input		190	1010	μA
					Resonator connection		260	1090	
	I _{DD3} ^{Note 5}	STOP mode	T _A = -40°C				0.19	0.50	μA
			T _A = +25°C				0.24	0.50	
			T _A = +50°C				0.32	0.80	
			T _A = +70°C				0.48	1.20	
			T _A = +85°C				0.74	2.20	
			T _A = +105°C				1.50	10.20	

- Notes**
1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
 2. During HALT instruction execution by flash memory.
 3. When high-speed on-chip oscillator clock is stopped.
 4. When high-speed system clock is stopped.
 5. Not including the current flowing into the 12-bit interval timer and watchdog timer.
 6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as follows.

HS (High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz

V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

- Remarks**
1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
 2. f_{IH}: high-speed on-chip oscillator clock frequency
 3. Except temperature condition of the TYP. value is T_A = 25°C, other than STOP mode

(2) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)**($T_A = -40$ to $+105^\circ\text{C}$, $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCKp cycle time	t_{KCY1}	$t_{KCY1} \geq 4/f_{CLK}$	$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	334	ns
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	500	ns
SCKp high-/low-level width	t_{KH1}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	$t_{KCY1}/2-24$		ns
	t_{KL1}	$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	$t_{KCY1}/2-36$		ns
		$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	$t_{KCY1}/2-76$		ns
Slp setup time (to SCKp \uparrow) ^{Note 1}	t_{SIK1}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	66		ns
		$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	66		ns
		$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	113		ns
Slp hold time (from SCKp \uparrow) ^{Note 2}	t_{KSI1}		38		ns
Delay time from SCKp \downarrow to SOp output ^{Note 3}	t_{KSO1}	$C = 30\text{ pF}$ ^{Note 4}		50	ns

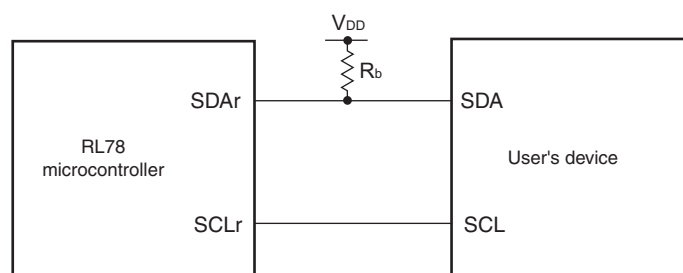
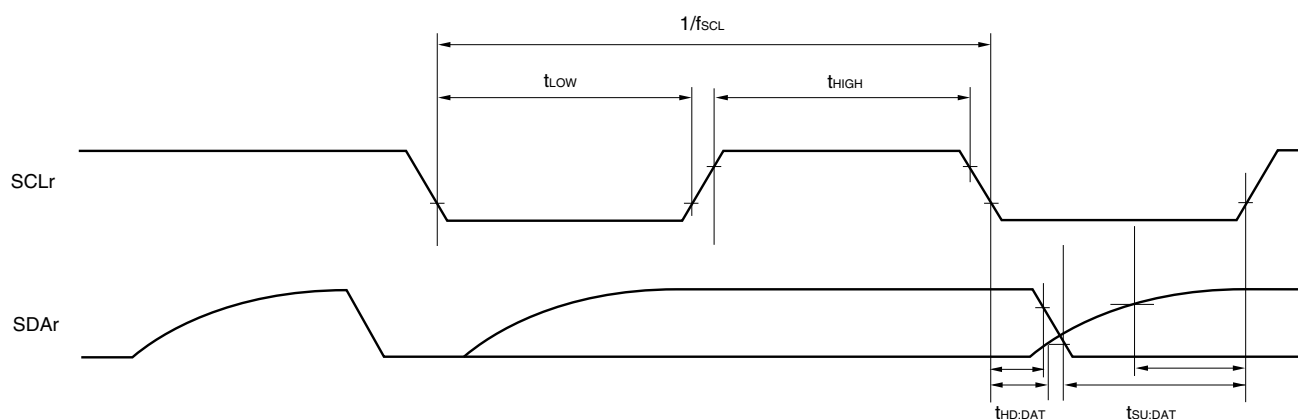
- Notes**
1. When $DAPmn = 0$ and $CKPmn = 0$, or $DAPmn = 1$ and $CKPmn = 1$. The Slp setup time becomes “to SCKp \downarrow ” when $DAPmn = 0$ and $CKPmn = 1$, or $DAPmn = 1$ and $CKPmn = 0$.
 2. When $DAPmn = 0$ and $CKPmn = 0$, or $DAPmn = 1$ and $CKPmn = 1$. The Slp hold time becomes “from SCKp \downarrow ” when $DAPmn = 0$ and $CKPmn = 1$, or $DAPmn = 1$ and $CKPmn = 0$.
 3. When $DAPmn = 0$ and $CKPmn = 0$, or $DAPmn = 1$ and $CKPmn = 1$. The delay time to SOp output becomes “from SCKp \uparrow ” when $DAPmn = 0$ and $CKPmn = 1$, or $DAPmn = 1$ and $CKPmn = 0$.
 4. C is the load capacitance of the SCKp and SOp output lines.

Caution Select the normal input buffer for the Slp pin and the normal output mode for the SOp and SCKp pins by using port input mode register 1 (PIM1) and port output mode registers 0, 1, 4 (POM0, POM1, POM4).

- Remarks**
1. p: CSI number (p = 00, 01, 11, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3)
 2. f_{MCK} : Serial array unit operation clock frequency
(Operation clock to be set by the serial clock select register m (SPSm) and the CKSmn bit of serial mode register mn (SMRmn). m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3))

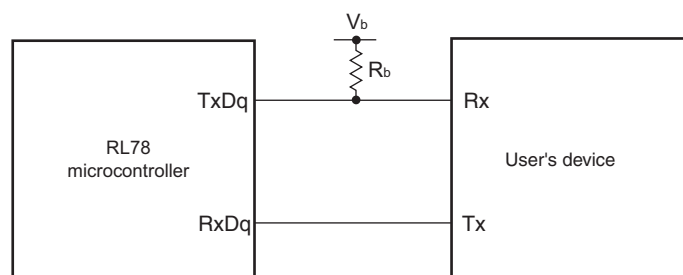
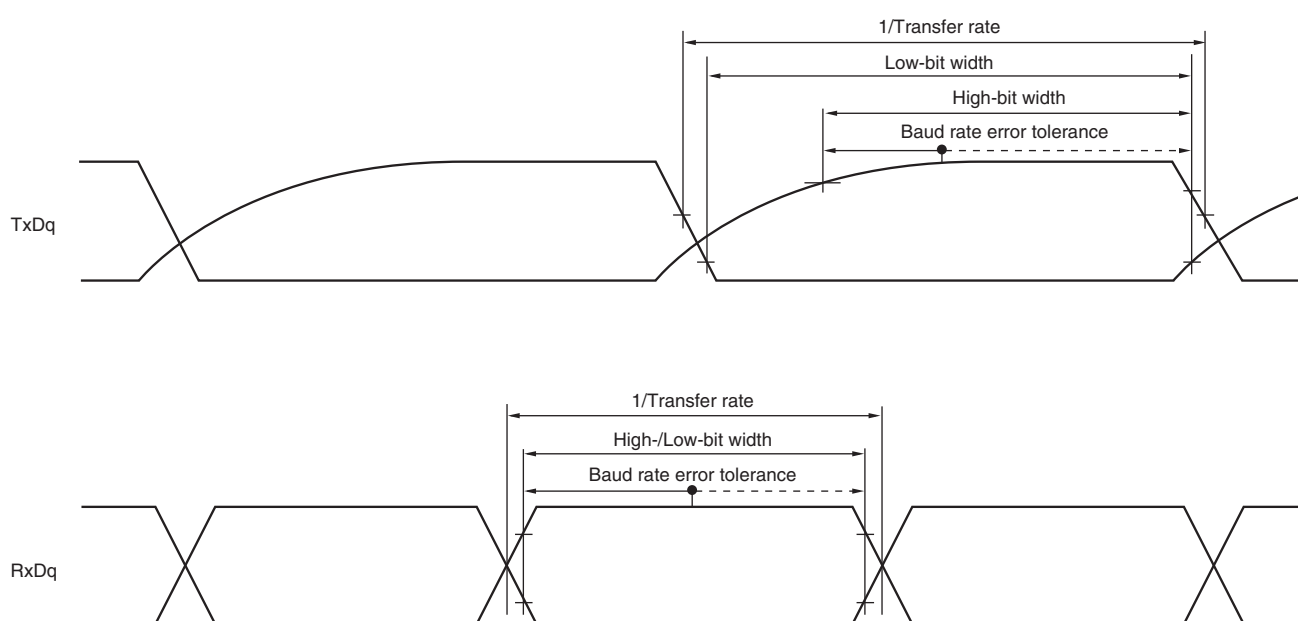
(4) During communication at same potential (simplified I²C mode)**($T_A = -40$ to $+105^\circ\text{C}$, $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCLr clock frequency	f_{SCL}	$C_b = 100\text{ pF}$, $R_b = 3\text{ k}\Omega$		100 ^{Note 1}	kHz
Hold time when SCLr = "L"	t_{LOW}	$C_b = 100\text{ pF}$, $R_b = 3\text{ k}\Omega$	4600		ns
Hold time when SCLr = "H"	t_{HIGH}	$C_b = 100\text{ pF}$, $R_b = 3\text{ k}\Omega$	4600		ns
Data setup time (reception)	$t_{\text{SU:DAT}}$	$C_b = 100\text{ pF}$, $R_b = 3\text{ k}\Omega$	$1/f_{\text{MCK}} + 580$ ^{Note 2}		ns
Data hold time (transmission)	$t_{\text{HD:DAT}}$	$C_b = 100\text{ pF}$, $R_b = 3\text{ k}\Omega$	0	1420	ns

Notes 1. The value must also be equal to or less than $f_{\text{MCK}}/4$.**2.** Set $t_{\text{SU:DAT}}$ so that it will not exceed the hold time when SCLr = "L" or SCLr = "H".**Caution** Select the N-ch open drain output (V_{DD} tolerance) mode for SDAr by using port output mode register h (POMh).**Simplified I²C mode connection diagram (during communication at same potential)****Simplified I²C mode serial transfer timing (during communication at same potential)****Remarks 1.** R_b [Ω]: Communication line (SDAr) pull-up resistance C_b [F]: Communication line (SCLr, SDAr) load capacitance**2.** r: IIC number (r = 00, 01, 11, 20), h: = POM number (h = 0, 1, 4, 5)**3.** f_{MCK} : Serial array unit operation clock frequency

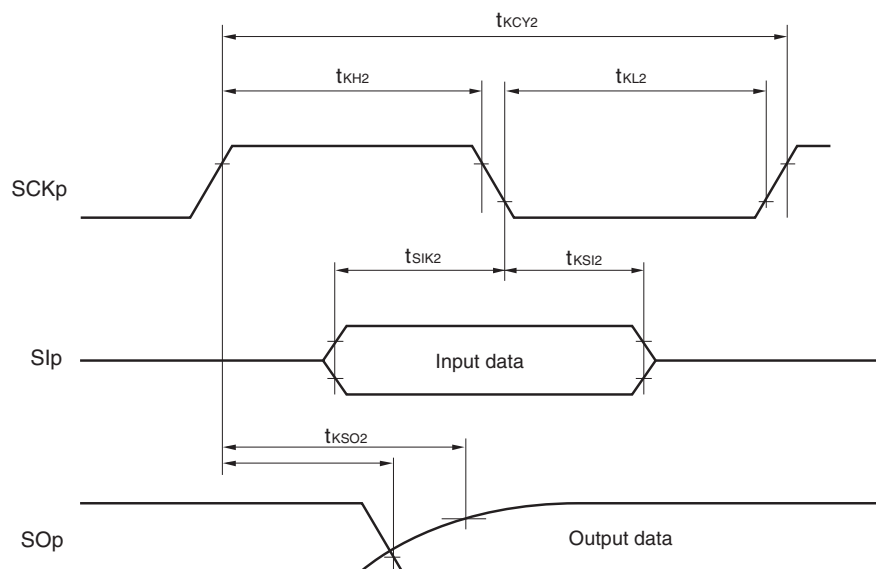
(Operation clock to be set by the serial clock select register m (SPSm) and the CKSmn bit of serial mode register mn (SMRmn).

m: Unit number (m = 0, 1), n: Channel number (0, 1, 3))

UART mode connection diagram (during communication at different potential)**UART mode bit width (during communication at different potential) (reference)**

- Remarks**
1. $R_b[\Omega]$: Communication line (TxDq) pull-up resistance, $C_b[F]$: Communication line (TxDq) load capacitance, $V_b[V]$: Communication line voltage
 2. q: UART number (q = 0 to 2), g: PIM and POM number (g = 0, 1)
 3. f_{MCK} : Serial array unit operation clock frequency
(Operation clock to be set by the serial clock select register m (SPSm) and the CKSmn bit of serial mode register mn (SMRmn).
m: Unit number, n: Channel number (mn = 00 to 03, 10, 11))
 4. UART0 of the 20- and 24-pin products supports communication at different potential only when the peripheral I/O redirection function is not used.

CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When $\text{DAPmn} = 0$ and $\text{CKPmn} = 1$, or $\text{DAPmn} = 1$ and $\text{CKPmn} = 0$.)



Remark p: CSI number ($p = 00, 20$), m: Unit number ($m = 0, 1$), n: Channel number ($n = 0$)

Notes 1. Excludes quantization error ($\pm 1/2$ LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When $AV_{REFP} < V_{DD}$, the MAX. values are as follows.

Overall error: Add ± 1.0 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

Zero-scale error/Full-scale error: Add $\pm 0.05\%$ FSR to the MAX. value when $AV_{REFP} = V_{DD}$.

Integral linearity error/ Differential linearity error: Add ± 0.5 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

4. Refer to **29.6.2 Temperature sensor/internal reference voltage characteristics**.

(2) When reference voltage (+) = $AV_{REFP}/ANI0$ ($ADREFP1 = 0$, $ADREFP0 = 1$), reference voltage (–) = $AV_{REFM}/ANI1$ ($ADREFM = 1$), target pin: ANI16 to ANI22

($T_A = -40$ to $+105^\circ\text{C}$, $2.4\text{ V} \leq AV_{REFP} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$, Reference voltage (+) = AV_{REFP} , Reference voltage (–) = $AV_{REFM} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES		8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution $AV_{REFP} = V_{DD}$ ^{Note 3}		1.2	± 5.0	LSB
Conversion time	t_{CONV}	10-bit resolution Target ANI pin: ANI16 to ANI22	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.125	39	μs
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.1875	39	μs
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17	39	μs
Zero-scale error ^{Notes 1, 2}	EZS	10-bit resolution $AV_{REFP} = V_{DD}$ ^{Note 3}			± 0.35	%FSR
Full-scale error ^{Notes 1, 2}	EFS	10-bit resolution $AV_{REFP} = V_{DD}$ ^{Note 3}			± 0.35	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution $AV_{REFP} = V_{DD}$ ^{Note 3}			± 3.5	LSB
Differential linearity error ^{Note 1}	DLE	10-bit resolution $AV_{REFP} = V_{DD}$ ^{Note 3}			± 2.0	LSB
Analog input voltage	V_{AIN}	ANI16 to ANI22	0		AV_{REFP} and V_{DD}	V

Notes 1. Excludes quantization error ($\pm 1/2$ LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When $AV_{REFP} \leq V_{DD}$, the MAX. values are as follows.

Overall error: Add ± 4.0 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

Zero-scale error/Full-scale error: Add $\pm 0.20\%$ FSR to the MAX. value when $AV_{REFP} = V_{DD}$.

Integral linearity error/ Differential linearity error: Add ± 2.0 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

(3) When reference voltage (+) = V_{DD} (ADREFP1 = 0, ADREFP0 = 0), reference voltage (–) = V_{SS} (ADREFM = 0), target pin: ANI0 to ANI3, ANI16 to ANI22, internal reference voltage, and temperature sensor output voltage

($T_A = -40$ to $+105^\circ\text{C}$, $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $V_{SS} = 0\text{ V}$, Reference voltage (+) = V_{DD} , Reference voltage (–) = V_{SS})

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES		8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution		1.2	± 7.0	LSB
Conversion time	t_{CONV}	10-bit resolution Target pin: ANI0 to ANI3, ANI16 to ANI22	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.125	39	μs
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.1875	39	μs
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17	39	μs
Conversion time	t_{CONV}	10-bit resolution Target pin: internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.375	39	μs
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.5625	39	μs
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17	39	μs
Zero-scale error ^{Notes 1, 2}	EZS	10-bit resolution			± 0.60	%FSR
Full-scale error ^{Notes 1, 2}	EFS	10-bit resolution			± 0.60	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution			± 4.0	LSB
Differential linearity error ^{Note 1}	DLE	10-bit resolution			± 2.0	LSB
Analog input voltage	V_{AIN}	ANI0 to ANI3, ANI16 to ANI22	0		V_{DD}	V
		Internal reference voltage (HS (high-speed main) mode)	V_{BGR} ^{Note 3}			V
		Temperature sensor output voltage (HS (high-speed main) mode)	V_{TMPS25} ^{Note 3}			V

Notes 1. Excludes quantization error ($\pm 1/2$ LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. Refer to **29.6.2 Temperature sensor/internal reference voltage characteristics**.